2SD2213

Silicon NPN Epitaxial, Darlington

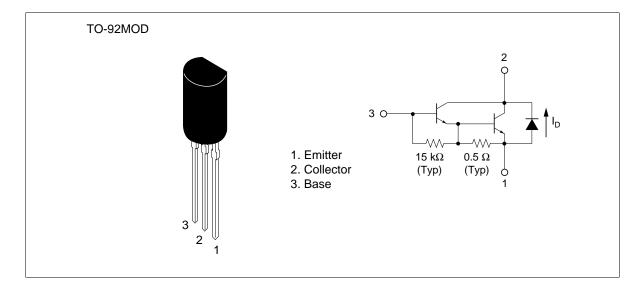
HITACHI

ADE-208-1165 (Z) 1st. Edition Mar. 2001

Application

Low frequency power amplifier

Outline





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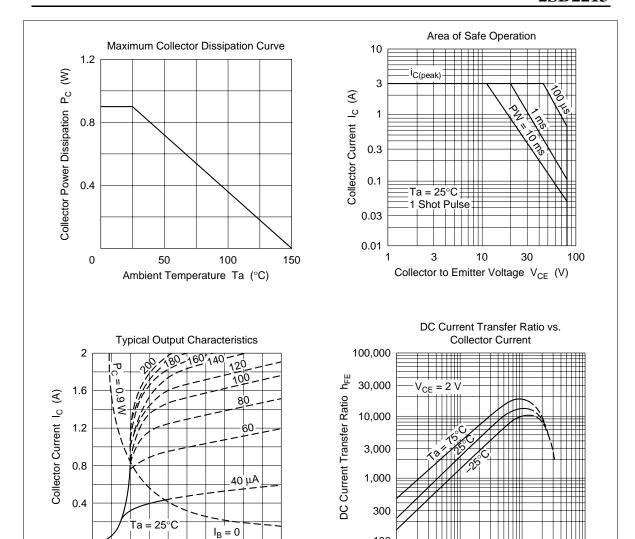
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	150	V
Collector to emitter voltage	V _{CEO}	80	V
Emitter to base voltage	V_{EBO}	8	V
Collector current	I _c	1.5	А
Collector peak current	ic (peak)	3	А
Collector power dissipation	P _c	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
E to C diode forward current	I _D	1.5	А

Electrical Characteristics ($Ta = 25^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	150	_	_	V	$I_C = 1 \text{ mA}, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	80	_	_	V	$I_{C} = 10 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	8	_	_	V	$I_{\rm E} = 50 \text{ mA}, I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	5.0	μΑ	$V_{CB} = 120 \text{ V}, I_{E} = 0$
	I _{CEO}	_	_	5.0	μΑ	V _{CE} = 65 V, I _E = ∞
DC current transfer ratio	h_{FE}	2000	_	_		$V_{CE} = 2 \text{ V}, I_{C} = 0.15 \text{ A}^{*1}$
	h _{FE}	5000	_	30000		$V_{CE} = 2 \text{ V}, I_{C} = 1 \text{ A}^{*1}$
	h _{FE}	1000	_	_		$V_{CE} = 2 \text{ V}, I_{C} = 1.5 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	1.5	V	$I_{C} = 1 A^{*1}, I_{B} = 1 mA$
Base to emitter saturation voltage	$V_{BE(sat)}$	_	_	2.0	V	$I_{C} = 1 \text{ A}^{*1}, I_{B} = 1 \text{ mA}$
E to C diode forward voltage	V_{D}	_	_	3.0	V	I _D = 1.5 A* ¹

Note: 1. Pulse test



0

2

Collector to Emitter Voltage V_{CE} (V)

3

100 _____ 0.01

0.03

0.1

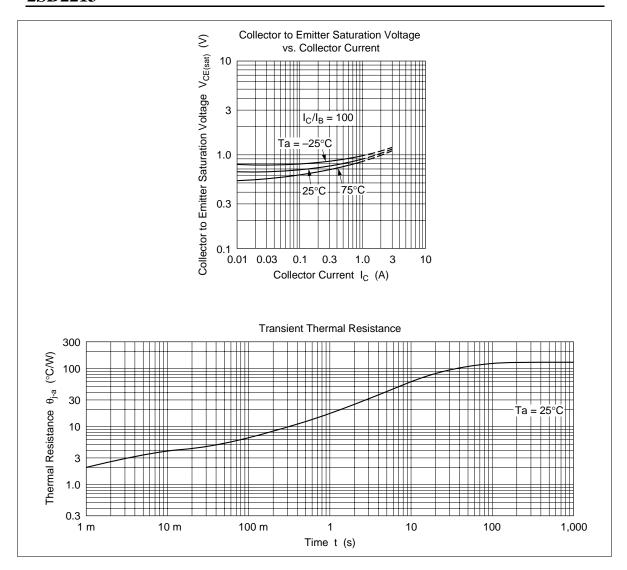
0.3

Collector Current I_C (A)

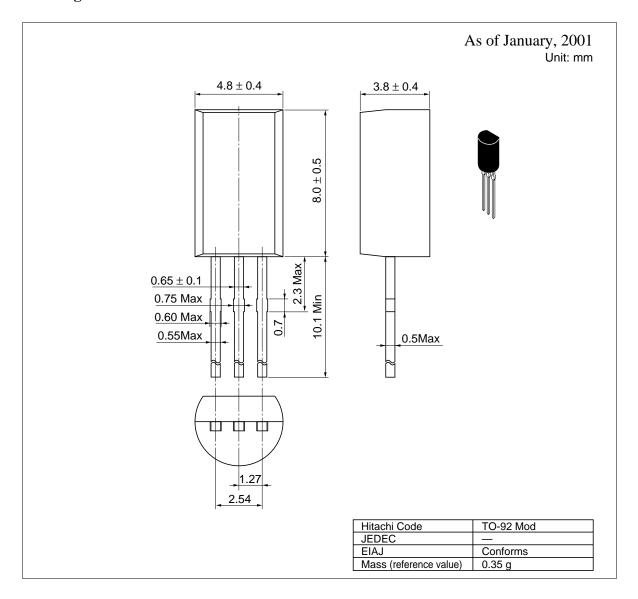
1.0

10

2SD2213



Package Dimensions



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